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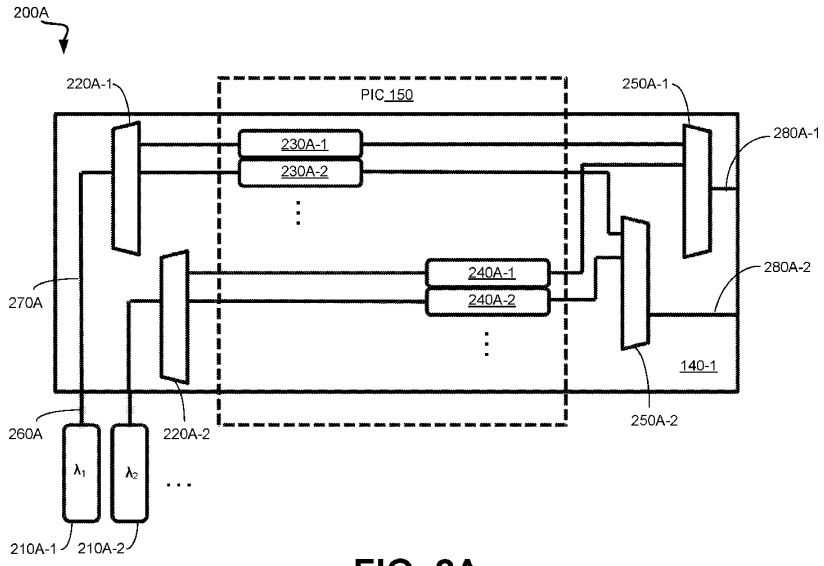



FIG. 2A

(57) Abstract: Embodiments of the present disclosure relate to optical systems. And the embodiments provide a system including: an interconnect comprising at least one power splitter; and a photonic integrated circuit (PIC) disposed on the interconnect, the PIC comprising at least one set of modulators, and a method including: obtaining at least one interconnect comprising at least one power splitter; obtaining at least one PIC comprising at least one set of modulators; and forming a device comprising the at least one interconnect and the at least one PIC.

*[Continued on next page]*

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